



DDR4 DIMM

TE Internal #: 2309411-1

SO DIMM Sockets, Small Outline (SO), Stack Height .315 in [8 mm],

Right Angle Module Orientation, 260 Position, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM SOCKETS



DRAM Type: **Small Outline (SO)**

Stack Height: **8 mm [ .315 in ]**

Module Orientation: **Right Angle**

Connector System: **Cable-to-Board**

Number of Positions: **260**

[All DDR4 SO DIMM SOCKETS \(39\)](#)

**Features**

**Product Type Features**

DRAM Type	Small Outline (SO)
Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board

**Configuration Features**

Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	260

**Electrical Characteristics**

DRAM Voltage	1.2 V
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**Signal Characteristics**

SGRAM Voltage	1.2 V
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**Body Features**

Ejector Location	Both Ends
Retention Post Material	Stainless Steel
Latch Material	High Temperature Thermoplastic



Retention Post Location	Both Ends
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Module Key Type	Offset Left
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Ejector Type	Locking
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Connector Profile	High
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#### Contact Features

Memory Socket Type	Memory Card
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Contact Underplating Material	Nickel
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PCB Contact Termination Area Plating Material	Gold Flash
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Contact Base Material	Copper Alloy
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Contact Mating Area Plating Material	Gold Flash
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Contact Current Rating (Max)	.5 A
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#### Termination Features

Insertion Style	Cam-In
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#### Mechanical Attachment

Mating Alignment Type	Standard Keying
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PCB Mounting Style	Surface Mount
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PCB Mount Retention	With
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PCB Mount Retention Type	Solder Peg
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Connector Mounting Type	Board Mount
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#### Housing Features

Housing Material	High Temperature Thermoplastic
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Housing Color	Black
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Centerline (Pitch)	.5 mm, 5.4 mm, 6.1 mm [.02 in]
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#### Dimensions

Stack Height	8 mm [.315 in]
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Row-to-Row Spacing	8.2 mm [.322 in]
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#### Usage Conditions

Operating Temperature Range	-55 – 85 °C [-67 – 185 °F]
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#### Operation/Application

Circuit Application	Power
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#### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	500
Packaging Method	Tape & Reel

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts





## Also in the Series | **DDR4 DIMM**



[DIMM Sockets\(69\)](#)



[SO DIMM Sockets\(39\)](#)

### Documents

#### Product Drawings

[DDR4 SODIMM 260P 8.0H STD](#)

English

#### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2309411-1\\_1.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309411-1\\_1.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309411-1\\_1.3d\\_stp.zip](#)

English

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#### Product Specifications

[Application Specification](#)

English

#### Product Environmental Compliance

[Product Compliance](#)

English

[Product Compliance](#)

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